

# Liebert XDA Parts Manual



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## 1. Product Description

*Increased Cooling Power for Rack Enclosures and High Heat Density Areas.*

Liebert X-treme Density heat removal system is designed to address the higher heat loads generated by densely populated electronic rack enclosures. It can cool more than 30 kW per rack. Individual modules can improve enclosure airflow or cool hot spots, or zones. The modules in the Liebert XD system use a unique heat rejection process, using a pumped refrigerant. It operates at low pressure and becomes a gas at room temperatures, making it ideal for use around electronic equipment. Liebert XD complement the precision cooling provided by Liebert Deluxe System/3 or Liebert DS, and are built with the quality and features you expect from Liebert.

**Liebert XDO** — Overhead Fan Coil: This ceiling-installed unit is placed above the heat-emitting equipment, drawing hot air from the Hot Aisle and discharging cold air down into the Cold Aisle. Connects via flexible piping and uses pumped refrigerant technology.

**Liebert XDV** — Vertical Top Cooler: The XDV is installed above or on the rack enclosure. It draws in hot air from inside the enclosure or from the Hot Aisle. It then cools the air and discharges it down into the Cold Aisle. Connects via flexible piping and uses pumped refrigerant technology.

**Liebert XDH** — Horizontal Row Cooler: The XDH is placed in line with rack enclosures and air from the hot aisle is drawn in through the rear of the unit, cooled, and discharged into the cold aisle where the electronic equipment air inlets are located. Connects via flexible piping and uses pumped refrigerant technology.

**Liebert XD CoolFrame** — Rack Cooler: The Liebert XD CoolFrame is designed and performance certified when attached to the back of the Egenera BladeFrame EX rack. It cools the exhaust air from the rack before the air enters the room. Connects via flexible piping to the Liebert XD system and uses pumped refrigerant technology. Liebert is a member of Egenera Inc. Assured Solution Alliance program. For more information on Egenera or their BladeFrame EX, visit [www.egenera.com](http://www.egenera.com)

**Liebert XDP** — Pumping Unit: When a building chilled water system is available, the XDP serves as an intermediary, to isolate the building chilled water circuit from the pumped refrigerant circuit. It circulates the refrigerant to the cooling modules at a temperature always above the actual dew point to prevent condensation.

**Liebert XDC** — Refrigerant Chiller: The XDC is an indoor unit that connects directly to the modules via the pumped refrigerant circuit. It circulates the refrigerant to the cooling modules at a temperature always above the actual dew point to prevent condensation.

**Liebert XD Piping:** The XD Piping is pre-fabricated distribution piping that is installed in anticipation of a growing and changing system. XD cooling modules are added as required and are quickly made operational with flexible connection piping with quick-connect fittings. The flexible connection piping also allows the cooling modules to be re-positioned without interruption in operation. Liebert XD Piping makes the system adaptive and provides for future expansion and simplifies both the installation of additional units and the reconfiguration of components as needs change.

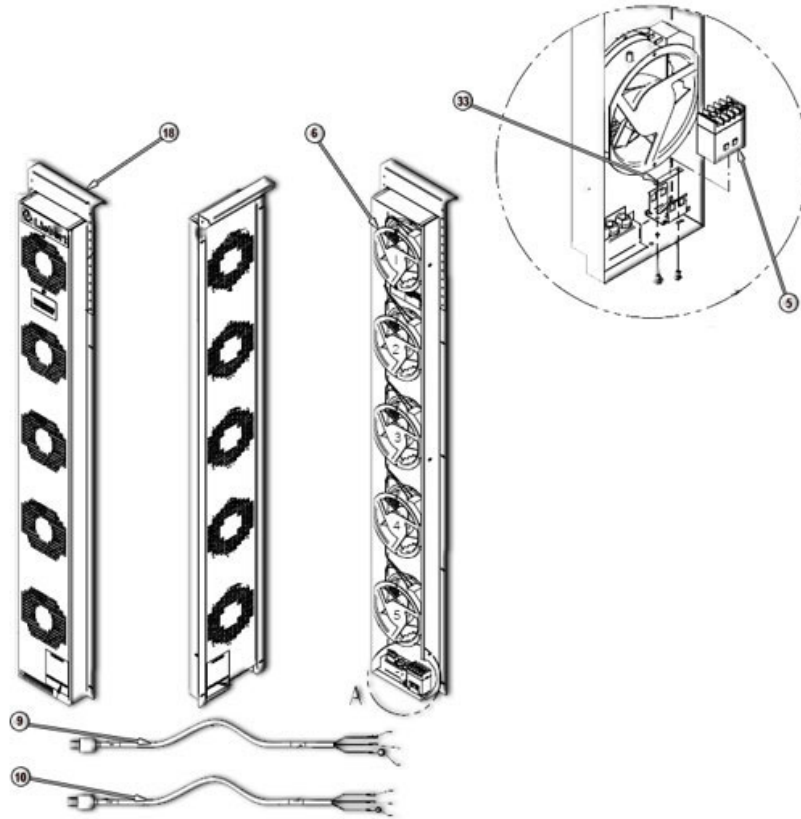
**Liebert XDA** — Air Flow Enhancer: Lightweight fan unit is mounted to the exhaust side of a rack enclosure. The XDA, that is compatible with most rack enclosures, increases the airflow through densely populated enclosures, past congested cabling, thus removing hot spots within the enclosure that can threaten the uptime of critical systems.

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*Features*

- Can Cool More Than 30 kW per rack
- Utilizes Pumped Refrigerant Technology
- Energy Efficient
- Intelligent Controls of the Refrigerant
- Floor Space Efficient
- Scalable and Flexible

## 2. XDA Air Mover Assembly



Item	Part #	Description	Quantity
1	180811P1	RELAY 4P 120V 2NO2NC	1
	180811P2	RELAY 4P 230V 2NO/2NC	1
6	5C10877P2	FAN 240CFM 220/230VAC 50/60HZ	5
	5C10877P1	FAN 240CFM 115V	5
9	177309G1	CORD PWR IEC 320 SJO W/TERMS	1
	177025G1	CORD PWR 18/3 SJO W/TERMS PRI	1
10	177310G1	CORD PWR IEC 320 SJO W/TERMS	1
	177024G1	CORD PWR 18/3 SJO W/TERMS PRI	1
18	176698P1	BRACKET SEC MOUNT AIRMOVER	1
33	5C10877P2	FAN 240CFM 220/230VAC 50/60HZ	5
	180849P1	BRACKET RELAY MTG OMRON G7J	1

### 3. Parts Gallery

#### Airmover Assembly

			
1C24870P1	155364P1	176698P1	180849P1
			
177309G1	177310G1		

#### 4. Revision Page

Revision Date	Modification	Details
01/2011		Manual Conversion